QH-Series H-Pin Socket

Accelerated life testing solution



The QH-Series socket is available for all available QFN products on the market. Designed to meet the rigors of accelerated life testing applications with socket 40 part numbers available. The QH-Series is a fully molded socket body and lid to meet the wide variety of burn-in test applications.

This socket also uses the H-Pin contact technology providing wide RF performance capabilities and exceptional DC characteristics. The QH-Series socket checks all the boxes: high frequency, high current, high temperature, low inductance, and low loss. These features result in lowering the cost of test.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

Benefits

- Industry proven design, in-house tooling, molding and machining, with 100% automated assembly.
- Extensive catalog of components and configurable options
- H-Pin offers unmatched DC performance.

Feature Options

- Small socket footprint
- HAST venting features
- Reverse seating plane
- Max component clearance under the DUT
- 2 or 3 plate systems
- High temperature materials for above 200 °C applications

QH-Series socket specifications

Mechanical Properties:

Pitch: ≥0.35 mmPackage Size:

QFN: 2 mm to 12 mm

■ **Pin count**: 200

■ Temperature: -55 °C to 260 °C

Electrical Properties

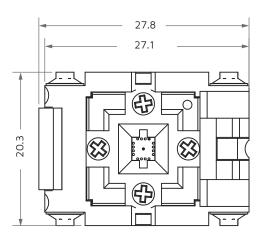
Contact Resistance: 35 mΩ

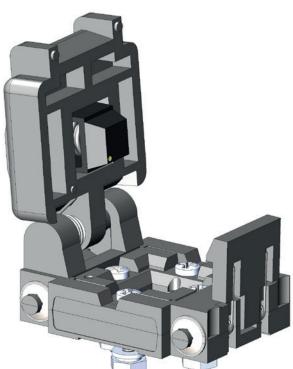
■ Current Carrying Capacity: up to 2.9 A

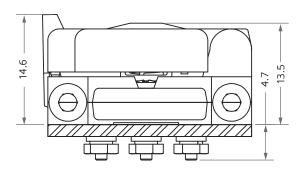
Materials

Contact: BeCu/Au platedSpring: SS/Au platedSocket: Engineering plastics

QH-Series socket dimensions







Dimensions are in mm.



more > smithsinterconnect.com

